

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$ max	I_D max $T_A = +25^\circ\text{C}$ (Note 5)
40V	31m Ω @ $V_{GS} = 10\text{V}$	7.0A
	50m Ω @ $V_{GS} = 4.5\text{V}$	5.6A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

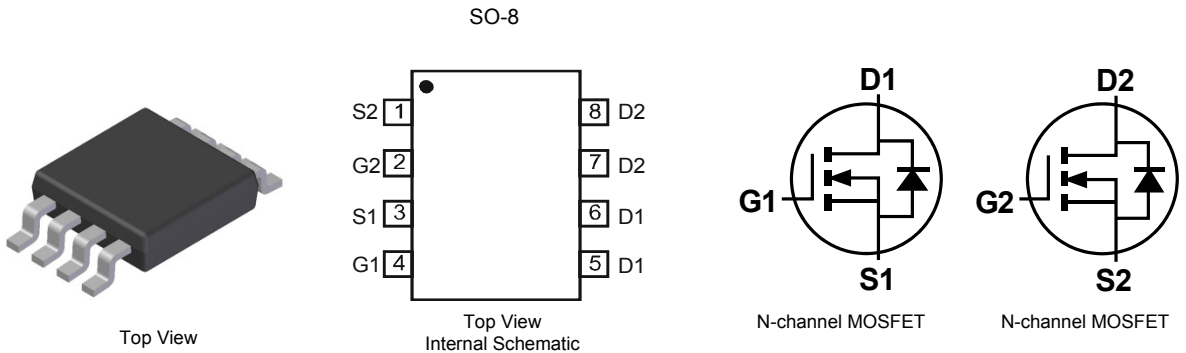
- Motor control
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low On-Resistance
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish — Matte Tin annealed over Copper leadframe.
Solderable per MIL-STD-202, Method 208 **e3**
- Weight: 0.072 grams (approximate)

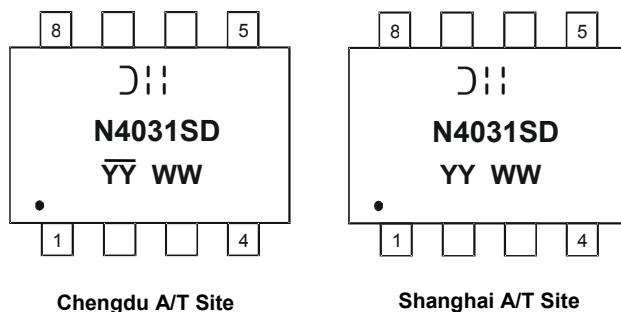


Ordering Information (Note 4)

Part Number	Case	Packaging
DMN4031SSD-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



011 = Manufacturer's Marking
 N4031SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 13 = 2013)
 WW = Week (01 - 53)
 YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Units
Drain-Source Voltage				V _{DSS}	40	V
Gate-Source Voltage				V _{GSS}	±20	V
Continuous Drain Current (Note 5)	V _{GS} = 10V	Steady State	T _A = +25°C	I _D	5.2	A
			T _A = +70°C		4.1	
Continuous Drain Current (Note 5)	V _{GS} = 4.5V	Steady State	T _A = +25°C	I _D	4.3	A
			T _A = +70°C		3.4	
Continuous Drain Current (Note 6)	V _{GS} = 10V	Steady State	T _A = +25°C	I _D	7.0	A
			T _A = +70°C		5.6	
Continuous Drain Current (Note 6)	V _{GS} = 4.5V	Steady State	T _A = +25°C	I _D	5.8	A
			T _A = +70°C		4.7	
Pulsed Drain Current (Note 7)				I _{DM}	20	A

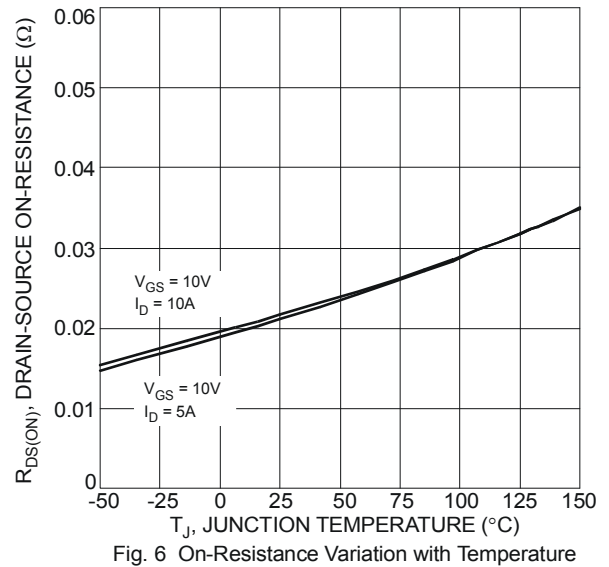
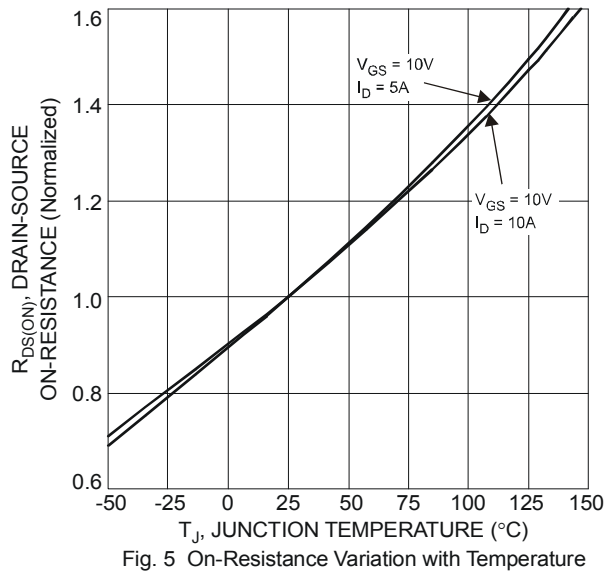
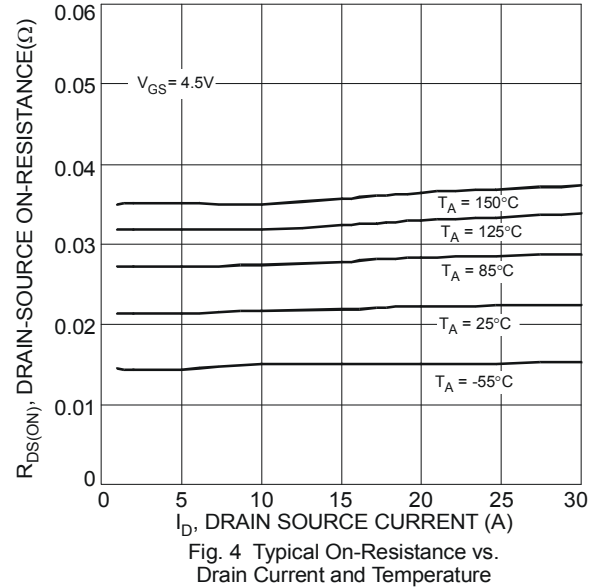
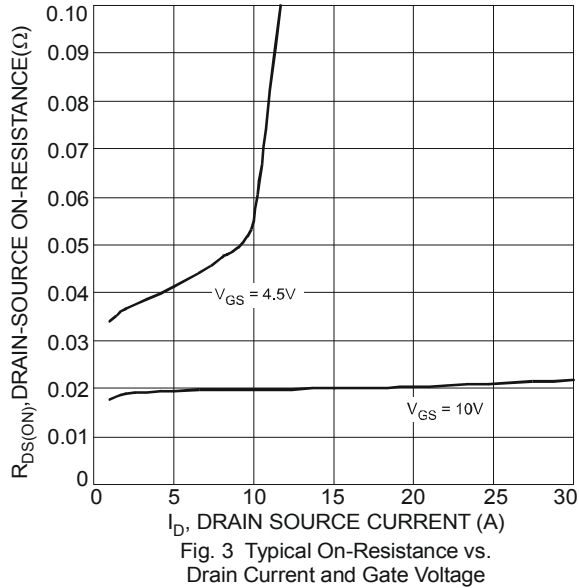
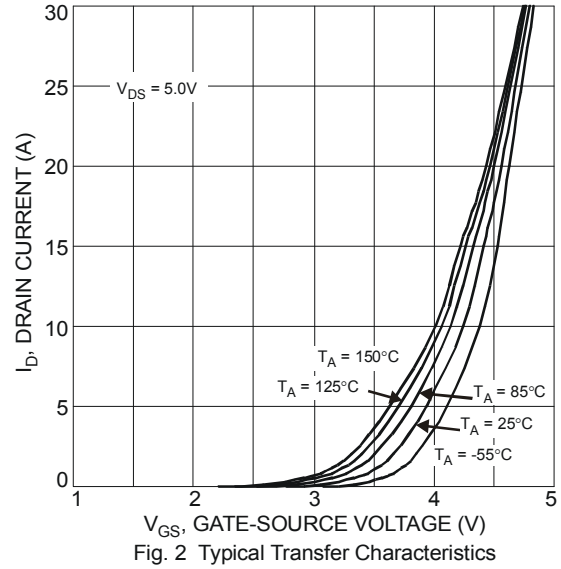
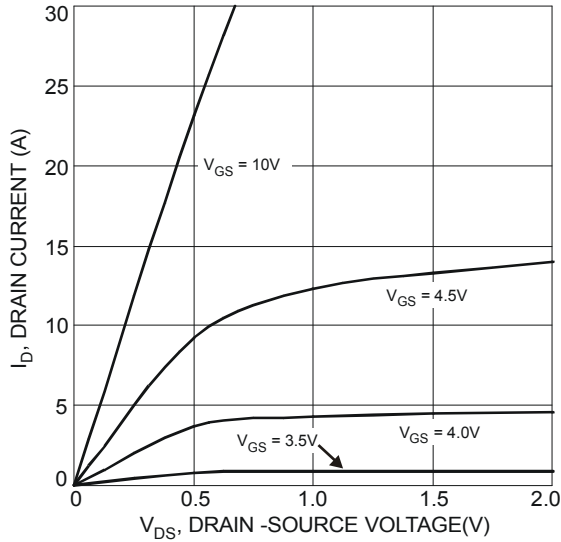
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P _D	1.42	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	R _{θJA}	88	°C/W
Total Power Dissipation (Note 6)	P _D	2.6	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	R _{θJA}	48	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	V _{GS} = 0V, I _D = 10mA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	1.6	2.4	3.0	V	V _{DS} = V _{GS} , I _D = 250μA
On-state drain current	I _{D(on)}	20	—	—	A	V _{GS} = 10V, V _{DS} = 5A
Static Drain-Source On-Resistance	R _{DS(on)}	—	19	31	mΩ	V _{GS} = 10V, I _D = 6A
		—	44	50		V _{GS} = 4.5V, I _D = 5A
Forward Transfer Admittance	Y _{fs}	—	11	—	S	V _{DS} = 5V, I _D = 6A
Diode Forward Voltage	V _{SD}	—	0.74	1.0	V	V _{GS} = 0V, I _S = 1A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	945	—	pF	V _{DS} = 20V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	69	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	58	—	pF	
Gate resistance	R _g	—	1.45	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	8.4	—	nC	V _{GS} = 10V, V _{DS} = 20V, I _D = 12A
Total Gate Charge (V _{GS} = 10V)	Q _g	—	18.6	—	nC	
Gate-Source Charge	Q _{gs}	—	3.3	—	nC	
Gate-Drain Charge	Q _{gd}	—	2.2	—	nC	V _{GS} = 10V, V _{DS} = 20V, R _L = 1.6Ω, R _G = 3Ω
Turn-On Delay Time	T _{D(on)}	—	6.4	—	ns	
Turn-On Rise Time	T _r	—	9.7	—	ns	
Turn-Off Delay Time	T _{D(off)}	—	19.8	—	ns	
Turn-Off Fall Time	T _f	—	3.1	—	ns	

- Notes:
- Device mounted on FR-4 PCB, with minimum recommended pad layout. The value in any given application depends on user's specific board design
 - Device mounted on 1" x 1" FR-4PCB with high coverage 1 oz. Copper, single sided.
 - Repetitive rating, pulse width limited by junction temperature.
 - Short duration pulse test used to minimize self-heating effect
 - Guaranteed by design. No subject to production testing.



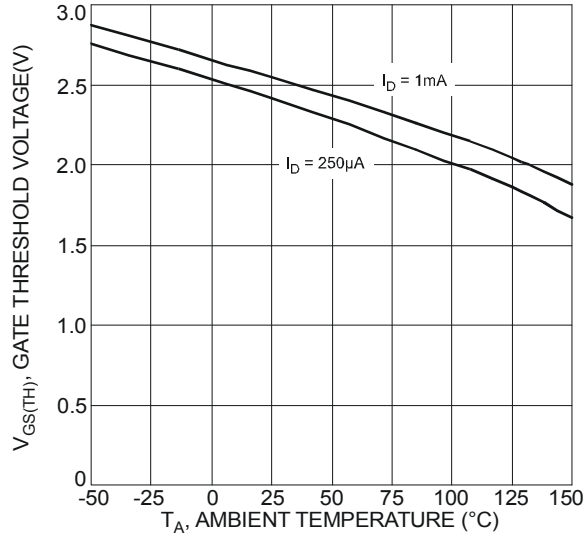


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

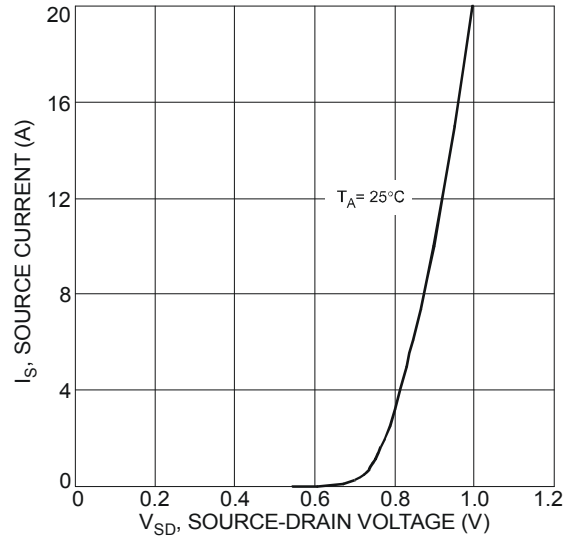


Fig. 8 Diode Forward Voltage vs. Current

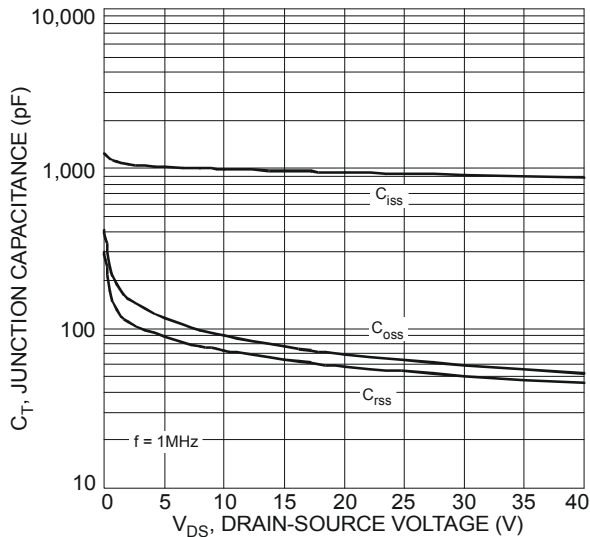


Fig. 9 Typical Junction Capacitance

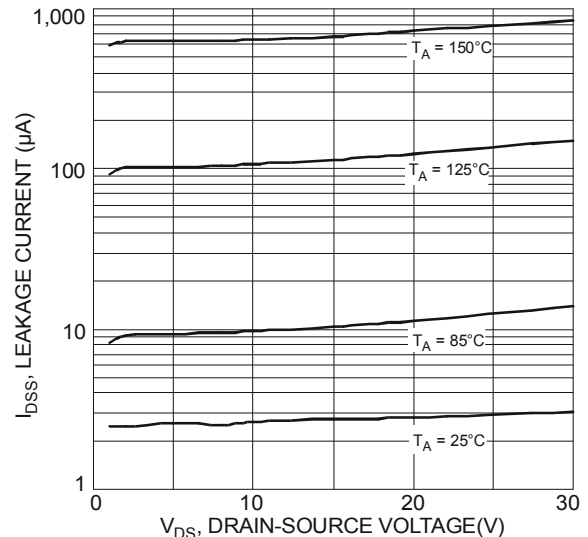


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

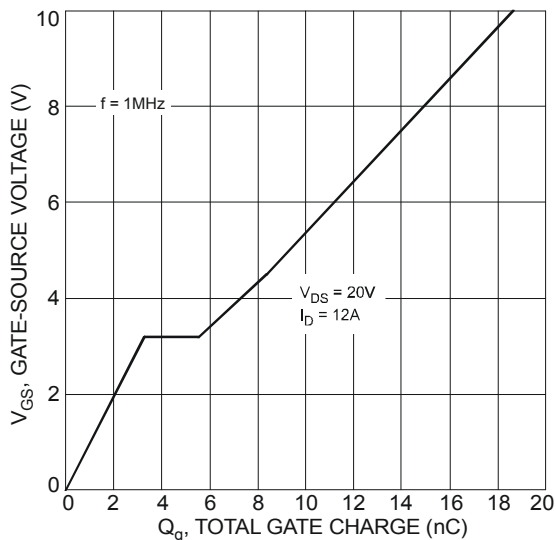


Fig. 11 Gate-Charge Characteristics

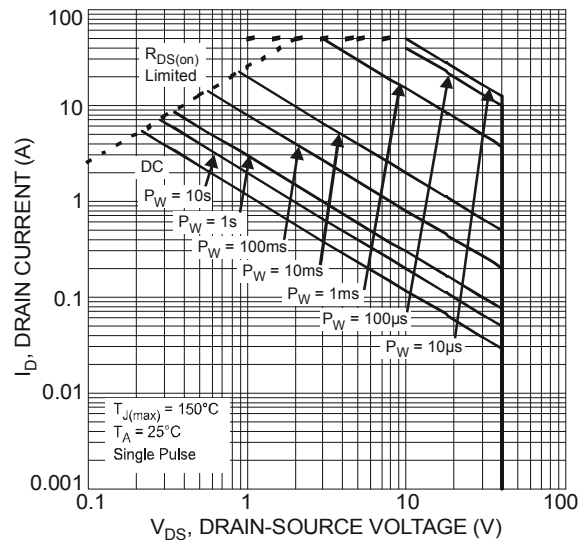
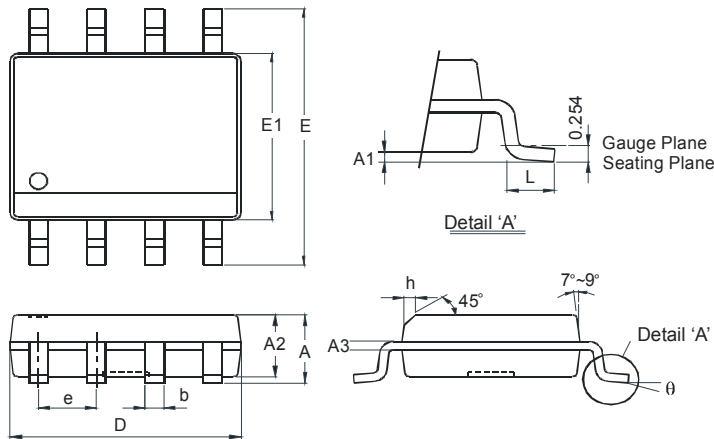


Fig. 12 SOA, Safe Operation Area

Package Outline Dimensions

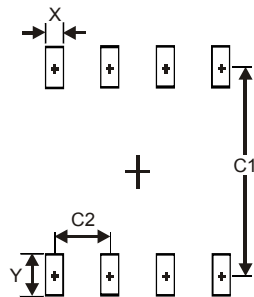
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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